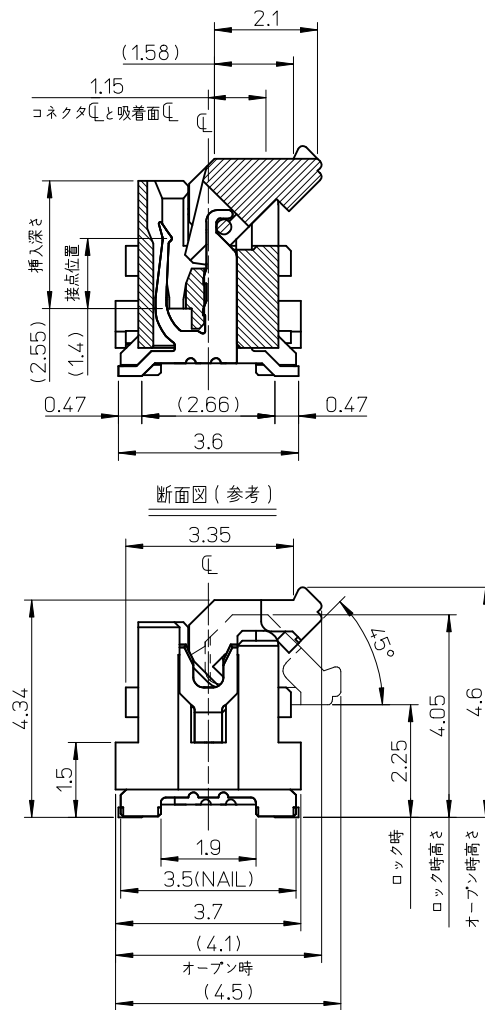
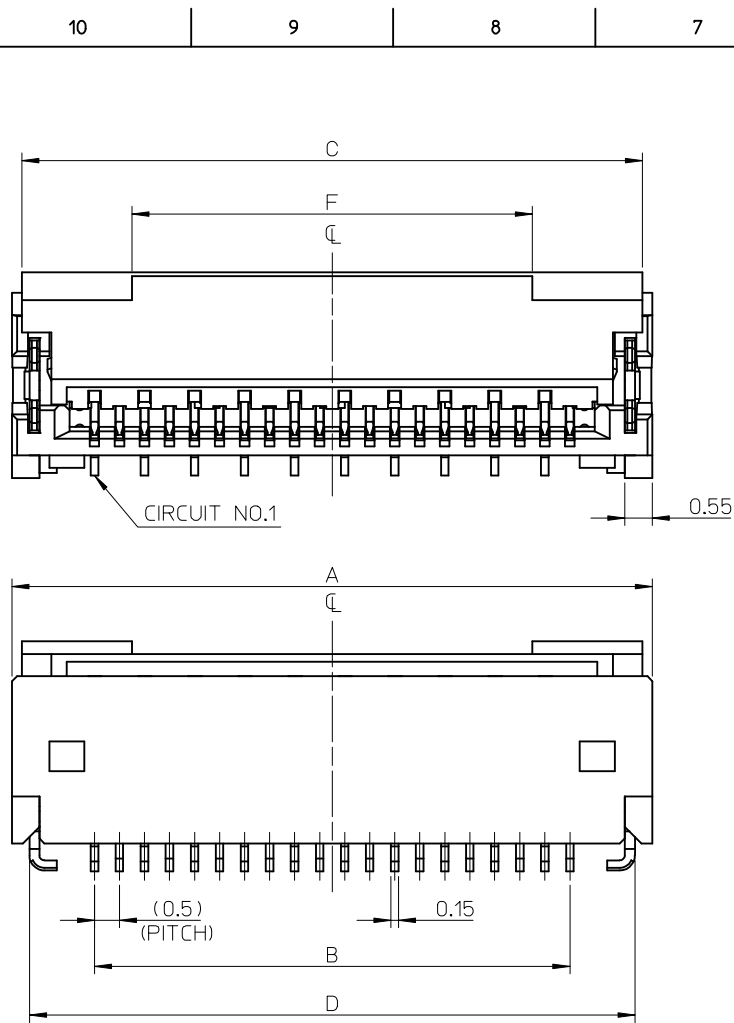




注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液晶ポリマー ガラス充填, UL94V-0(白)
HOUSING : LIQUID CRYSTAL POLYMER
GLASS FILLED, UL94V-0 (WHITE)
アクチュエータ : ポリアミド 9T, ガラス充填, UL94V-0(茶)
ACTUATOR : POLYAMIDE 9T, GLASS FILLED,
UL94V-0 (BROWN)
ターミナル : 銅合金(t=0.15)
TERMINAL : COPPER ALLOY
金具 : 銅合金(t=0.2)
FITTING NAIL : COPPER ALLOY

2. めっき仕様 PLATING

ターミナル TERMINAL

コンタクト部 : 部分金めっき(0.1μm以上)

テール部 : 部分金めっき

下地 : ニッケルめっき(1.0μm以上)

CONTACT AREA : SEPARATED GOLD PLATING
(0.1 MICROMETER MINIMUM)

SOLDER TAIL AREA : SEPARATED GOLD PLATING
UNDERPLATE : NICKEL OVERALL

金具 FITTING NAIL

ニッケル下地めっき

銅めっき(1.0μm以上)

ニッケルめっき(1.0μm以上)

TIN(Sn) OVER NICKEL(Ni) PLATING.

TIN PLATING (1.0 MICROMETER MINIMUM)

NICKEL PLATING (1.0 MICROMETER MINIMUM)

3. テールと金具を併せた平坦度は 0.1ミリメートル以下(リフロー前)

TAILS AND NAILS COPLANARITY
TO BE 0.1 MAX. (BEFORE REFLOW)

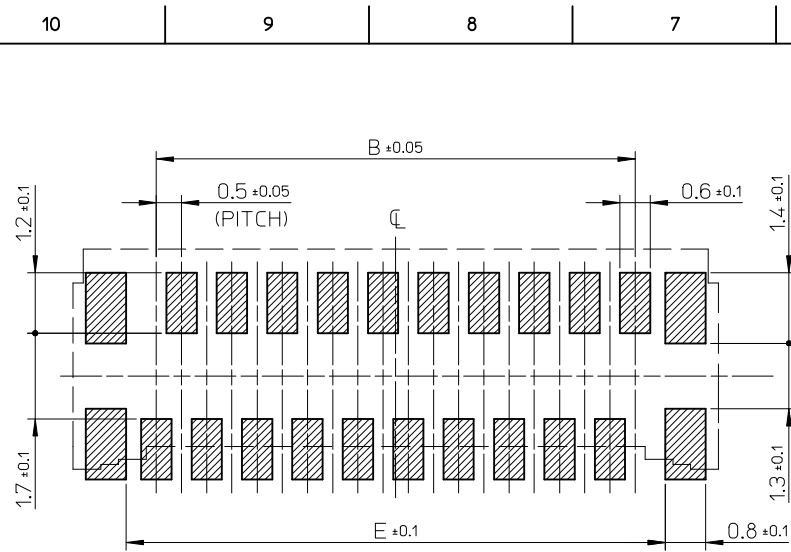
4. ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

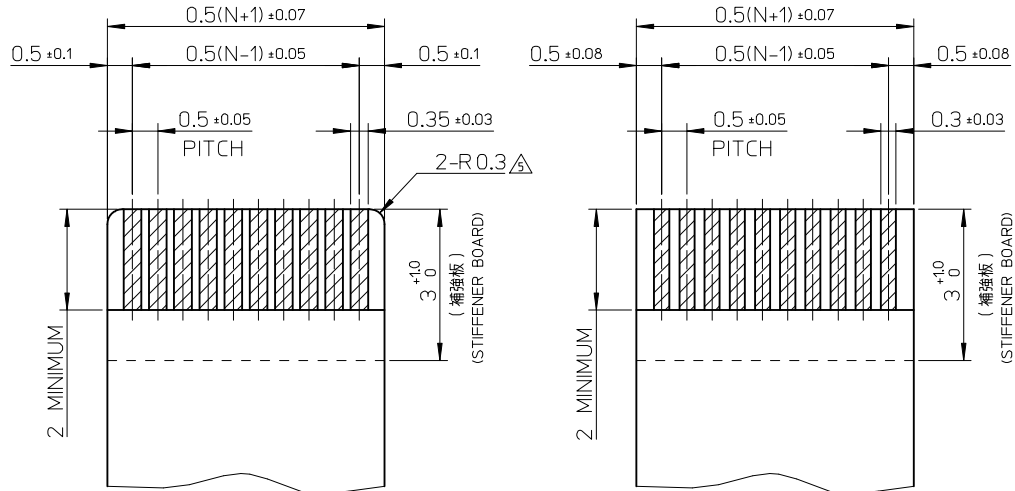
△ R0.3は、FPC導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED
TO PATTERN OF FPC.

8	35.7	37.1	37.4	34.5	37.8	501951-7019	70
	30.7	32.1	32.4	29.5	32.8	501951-6019	60
	25.7	27.1	27.4	24.5	27.8	501951-5019	50
	23.2	24.6	24.9	22	25.3	501951-4519	45
	20.7	22.1	22.4	19.5	22.8	501951-4019	40
	16.7	18.1	18.4	15.5	18.8	501951-3219	32
	15.7	17.1	17.4	14.5	17.8	501951-3019	30
	12.7	14.1	14.4	11.5	14.8	501951-2419	24
	11.7	13.1	13.4	10.5	13.8	501951-2219	22
	10.7	12.1	12.4	9.5	12.8	501951-2019	20
F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

REVISED EC NO: J2015-1526 DRAWN: AISHI CHKD: KAKAHASHI APPR: YNOGAWA 2015/05/18 2015/05/18 2015/05/20	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		0.25 UNDER		± 0.03	DRAWN BY	DATE	TITLE 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD)			
		0.25 OVER 0.5 UNDER		± 0.05	TRSUZUKI	2006/08/21				
		0.5 OVER 1.0 UNDER		± 0.1	CHECKED BY	DATE	molex			
		1.0 OVER 10 UNDER		± 0.2	HIRATA	2006/08/21				
		10 OVER 30 UNDER		± 0.25	APPROVED BY	DATE	DOCUMENT NO. SD-501951-003			
		30 OVER		± 0.3	MSASAO	2006/08/21				
		ANGULAR ±1 °			MATERIAL NO.		SEE CHART			SHEET NO. 1 OF 2
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



参考基板レイアウト (マウント面)
P.C. BOARD PATTERN DIMENSION (REF.)
(MOUNT AREA)



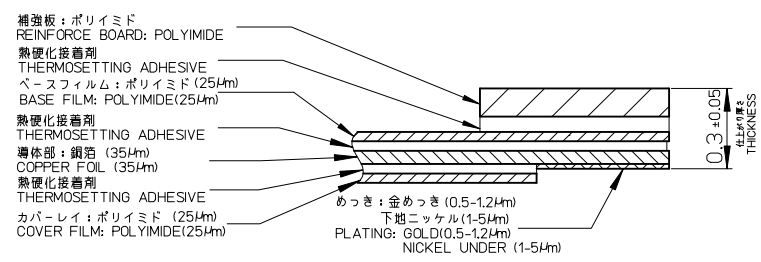
適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ± 0.05)
(THICKNESS: 0.3 ± 0.05)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ± 0.05)
(THICKNESS: 0.3 ± 0.05)

FPCについて ABOUT FPC

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25 μ mを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。

RECOMMENDED MATERIAL/THICKNESS.
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.
THERE IS A POSSIBILITY THAT THE PRESCRIPT TEMPERATURE OF FFC IS SET TO SINGLE IT.

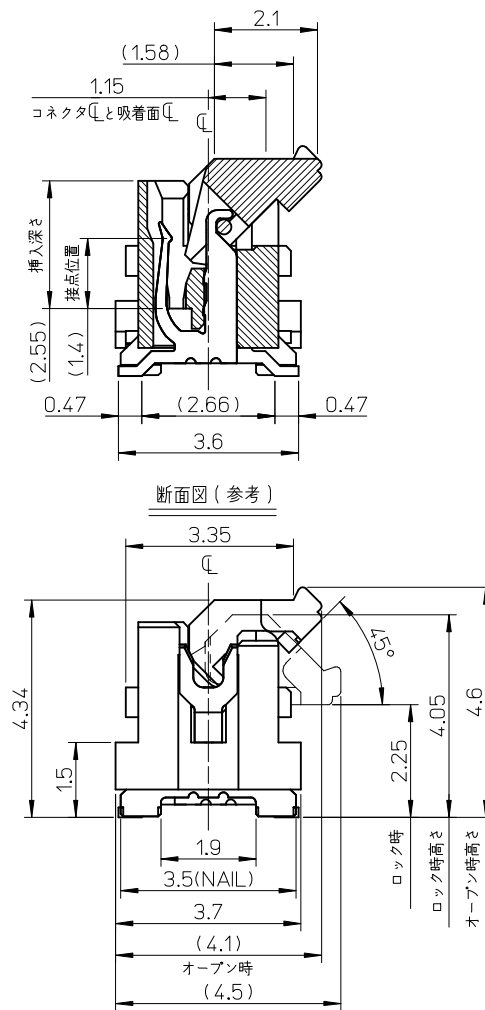
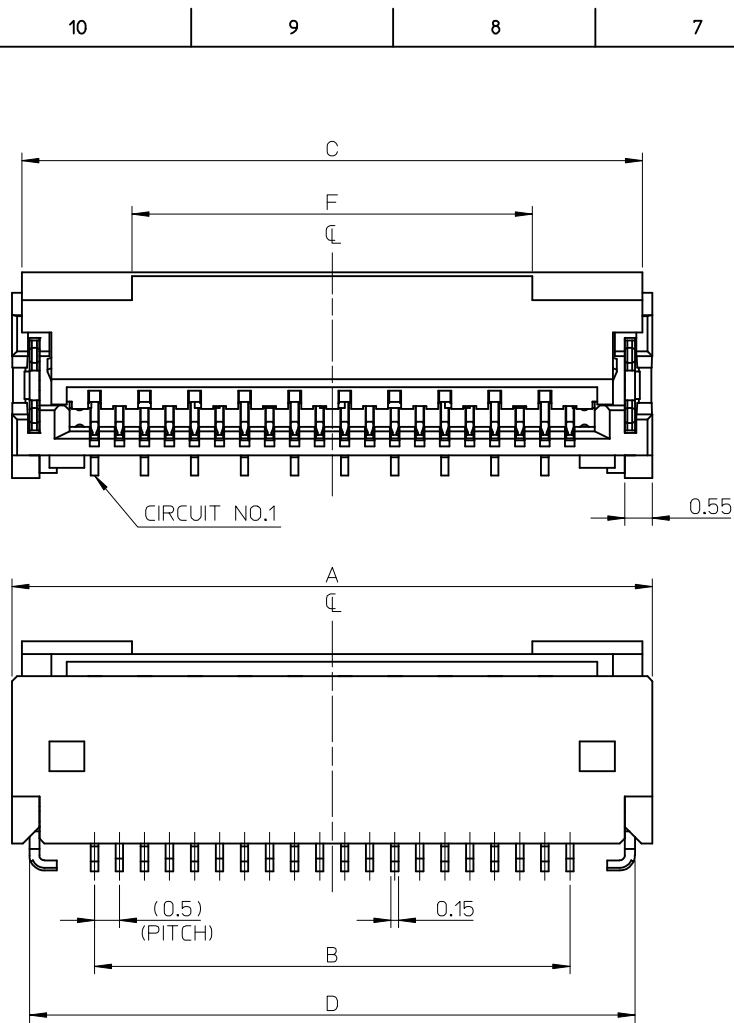


FPC構成推奨仕様
STRUCTURE OF FPC

FPC/FFCについて ABOUT FPC/FFC

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟箔銅35 μ mまたは50 μ mを推奨します。
FFCに規定された定格温度がFFC単体前提である場合が御座います。
コネクタと組み合わせての実使用において、接着層が劣化するなどの信頼性を満足できないケースを回避するため、
実機での評価/確認をお願い致します。
RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER
NOTE: WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FFC IS DETERIORATED ETC.)

SEE SHEET 1 OF 2 EC NO: J2015-1526 DRAWN BY: DRWNAISHI CHKD: TAKAHASHI APPR: YNOGAWA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY			SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER		±0.03	DRAWN BY		DATE	TITLE 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD)				
		0.25 OVER	0.5 UNDER	±0.05	TRSUZUKI		2006/08/21					
		0.5 OVER	1.0 UNDER	±0.1	CHECKED BY		DATE	molex				
		1.0 OVER	10 UNDER	±0.2	HHIRATA		2006/08/21					
		10 OVER	30 UNDER	±0.25	APPROVED BY		DATE	SD-501951-003				
		30 OVER	±0.3	MSASAO		2006/08/21						
		ANGULAR ±1 °			MATERIAL NO.			DOCUMENT NO.			SHEET NO.	
					SEE SHEET 1 OF 2						2 OF 2	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

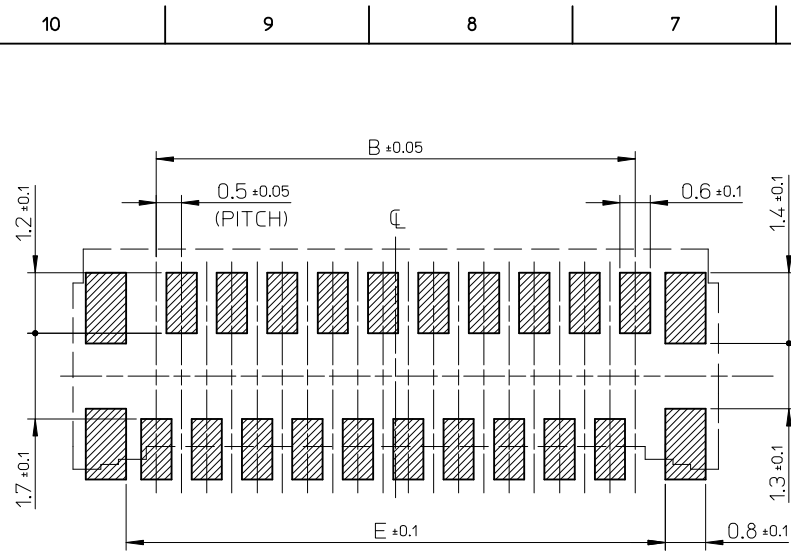


注記 NOTES

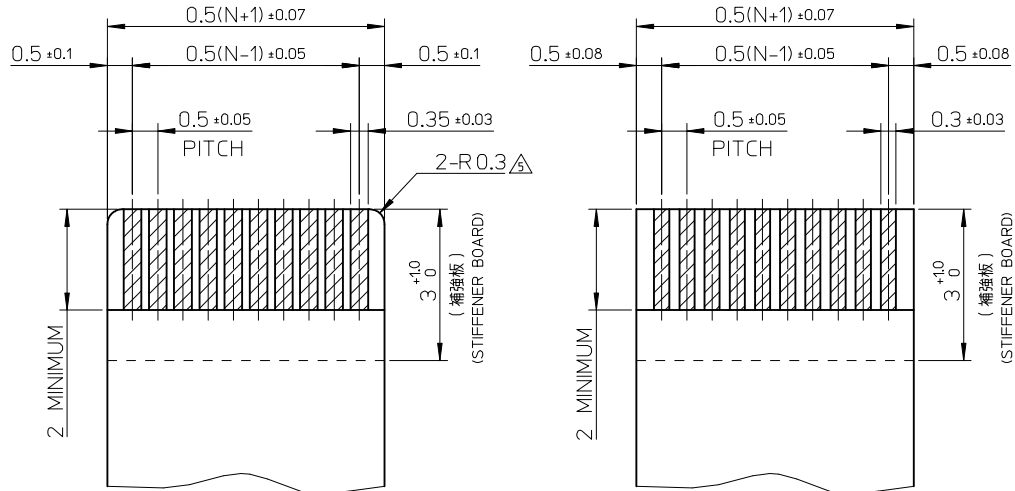
1. 使用材料 MATERIAL
ハウジング : 液晶ポリマー ガラス充填, UL94V-0(白)
HOUSING : LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0 (WHITE)
アクチュエータ : ポリアミド 9T, ガラス充填, UL94V-0(茶)
ACTUATOR : POLYAMIDE 9T, GLASS FILLED, UL94V-0 (BROWN)
ターミナル : 銅合金(t=0.15)
TERMINAL : COPPER ALLOY
金具 : 銅合金(t=0.2)
FITTING NAIL : COPPER ALLOY
2. めっき仕様 PLATING
ターミナル TERMINAL
コンタクト部 : 部分金めっき(0.1μm以上)
テール部 : 部分金めっき
下地 : ニッケルめっき(1.0μm以上)
CONTACT AREA : SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)
SOLDER TAIL AREA : SEPARATED GOLD PLATING UNDERPLATE : NICKEL OVERALL
金具 FITTING NAIL
ニッケル下地めっき
銅めっき(1.0μm以上)
ニッケルめっき(1.0μm以上)
TIN(Sn) OVER NICKEL(Ni) PLATING, TIN PLATING (1.0 MICROMETER MINIMUM)
NICKEL PLATING (1.0 MICROMETER MINIMUM)
3. テールと金具を併せた平坦度は 0.1ミリメートル以下(リフロー前)
TAILS AND NAILS COPLANARITY TO BE 0.1 MAX. (BEFORE REFLOW)
4. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
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	10.7	12.1	12.4	9.5	12.8	501951-2019	20
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REVISED EC NO: J2015-1526 DRAWN: AISHI CHKD: KATAHASHI APPR: YNOGAWA	2015/05/18 2015/05/18 2015/05/20	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
			0.25 UNDER		± 0.03	DRAWN BY	DATE	TITLE 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD) molex		
			0.25 OVER 0.5 UNDER		± 0.05	TRSUZUKI	2006/08/21			
			0.5 OVER 1.0 UNDER		± 0.1	CHECKED BY	DATE			
			1.0 OVER 10 UNDER		± 0.2	HHIRATA	2006/08/21			
			10 OVER 30 UNDER		± 0.25	APPROVED BY	DATE			
			30 OVER		± 0.3	MSASAO	2006/08/21	DOCUMENT NO. SD-501951-003	SHEET NO. 1 OF 2	
			ANGULAR ±1 °			MATERIAL NO.				
						SEE CHART				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



参考基板レイアウト (マウント面)
P.C. BOARD PATTERN DIMENSION (REF.)
(MOUNT AREA)



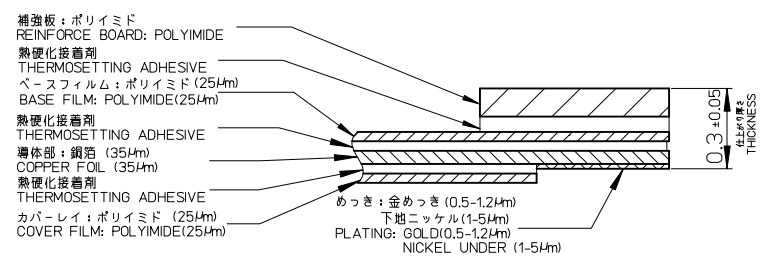
適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ± 0.05)
(THICKNESS: 0.3 ± 0.05)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ± 0.05)
(THICKNESS: 0.3 ± 0.05)

FPCについて ABOUT FPC

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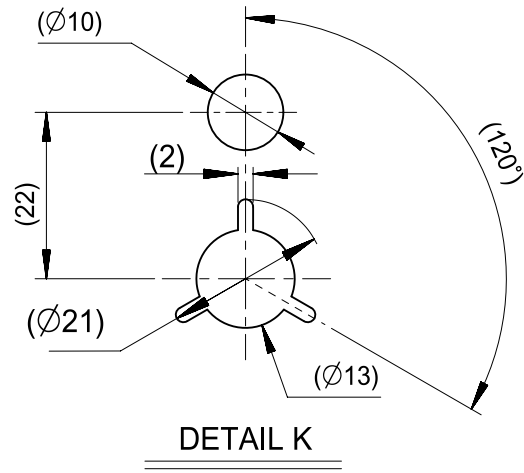
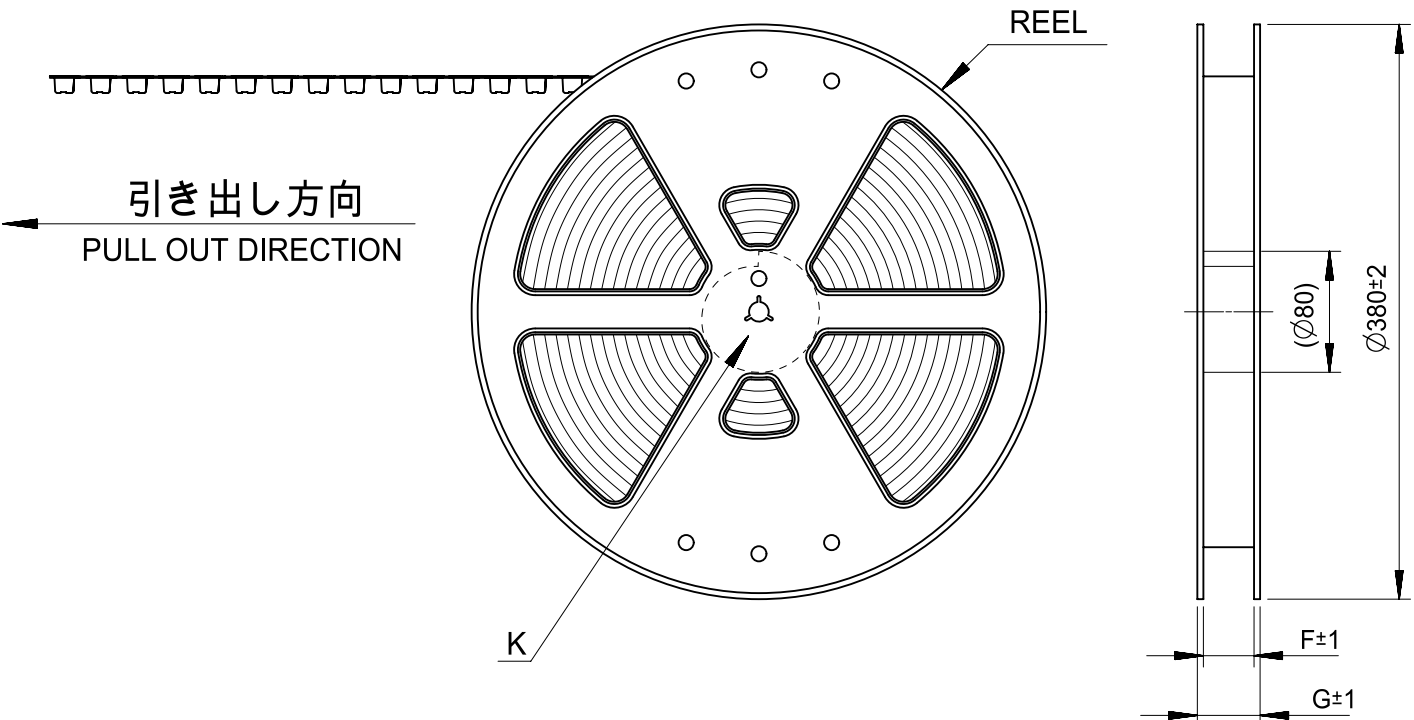


FPC構成推奨仕様
STRUCTURE OF FPC

FPC/FFCについて ABOUT FPC/FFC

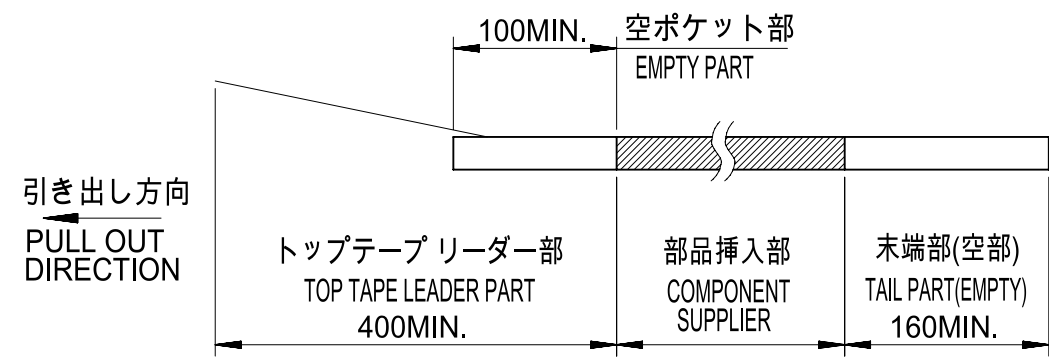
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SEE SHEET 1 OF 2 EC NO: J2015-1526 DRAWN: AISHI CHKD: TAKAHASHI APPR: YNOGAWA REV	DESCRIPTION 2015/05/18 2015/05/18 2015/05/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (GOLD)				
		0.25 OVER 0.5 UNDER	±0.05	TRSUZUKI	2006/08/21					
		0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE	molex				
		1.0 OVER 10 UNDER	±0.2	HIRATA	2006/08/21					
		10 OVER 30 UNDER	±0.25	APPROVED BY	DATE	SD-501951-003				
		30 OVER	±0.3	MSASAO	2006/08/21					
		ANGULAR ±1 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1 OF 2		2 OF 2				
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

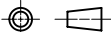


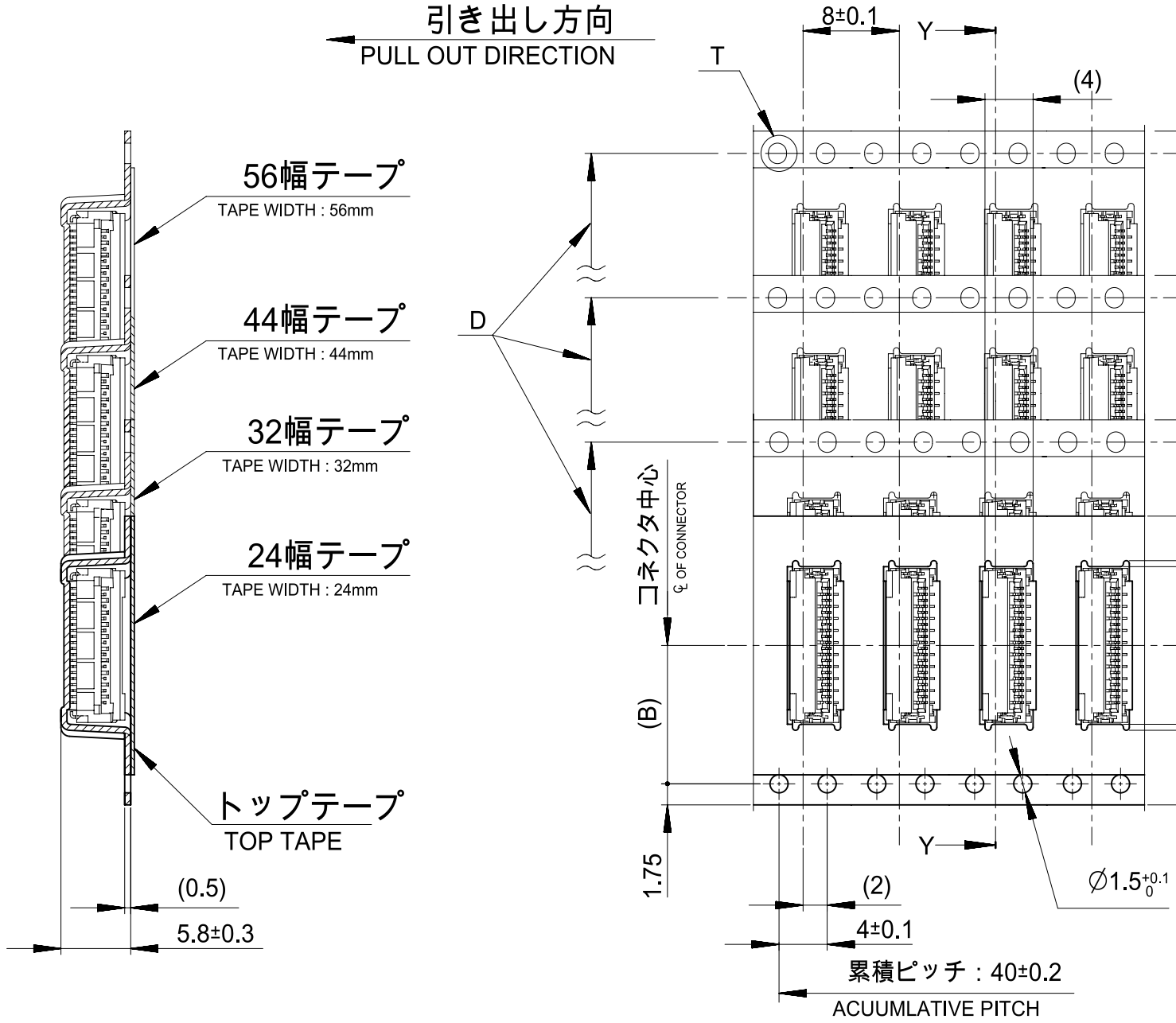
NOTES

1. 製品詳細寸法については図面 SD-501951-003を参照下さい。
FOR DIMENSIONS OF PRODUCT, REFER TO SD-501951-003.
2. 梱包数量：2000個/リール
NUMBER OF CONNECTORS：2000PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH

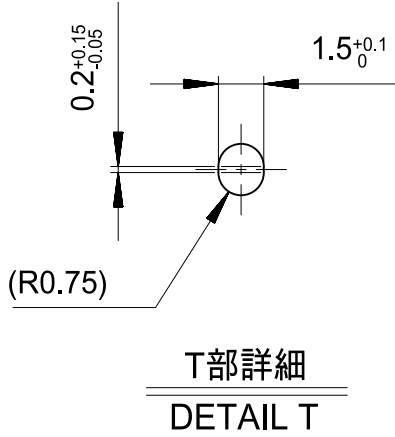


4. トップテープの剥離強度については、IEC60286-3に準拠
TOP TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
5. 材料 MATERIAL
キャリアテープ：ポリスチレン
CARRIER TAPE：POLYSTYRENE
トップテープ：ポリエチレンテレフタレート、ポリエチレン
TOP TAPE：POLYETHYLENE TEREPHTHALATE , POLYETHYLENE
リール：ポリスチレン<リサイクル材を含む>
REEL：POLYSTYRENE<RECYCLE MATERIAL CONTAINED>
6. ELV及びRoHS適合品 ELV AND RoHS COMPLIANT

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																
DIMENSION UNITS		SCALE		CURRENT REV DESC:			molex 0.5 FPC CONN. HSG ASSY E/O STRAIGHT EMBSTP PKG (GOLD)									
mm		10:1														
GENERAL TOLERANCES (UNLESS SPECIFIED)																
ANGULAR TOL		±	1.0 °		PRODUCT CUSTOMER DRAWING											
4 PLACES		±	0.05													
3 PLACES		±	0.1													
2 PLACES		±	0.2													
1 PLACE		±	0.25													
0 PLACES		±	0.3		DOCUMENT NUMBER			DOC TYPE	DOC PART	REVISION						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION			DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
							A3-SIZE		501951							



断面 Y-Y
SECTION Y-Y



61.4	57.4	56±0.3	52.4	39.1	26.2	38.1	501951-7010	70
				34.1		33.1	501951-6010	60
49.4	45.4	44±0.3	40.4	29.1	20.2	28.1	501951-5010	50
				26.1		25.6	501951-4510	45
				24.1		23.1	501951-4010	40
37.4	33.4	32±0.3	28.4	20.1	14.2	19.1	501951-3210	32
				19.1		18.1	501951-3010	30
				16.1		15.1	501951-2410	24
29.4	25.4	24±0.3	—	15.1	11.5	14.1	501951-2210	22
				14.1		13.1	501951-2010	20
G	F	E CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	CIRCUITS

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DIMENSION UNITS		SCALE		CURRENT REV DESC:			molex						
mm		10:1											
GENERAL TOLERANCES (UNLESS SPECIFIED)				EC NO: 601584 DRWN: SKAWAKAMI 2018/09/21 CHK'D: TRSUZUKI 2018/09/25 APPR: RTAKEUCHI 2018/12/25 INITIAL REVISION: DRWN: TRSUZUKI 2006/08/31 APPR: HHIRATA 2006/09/05									
ANGULAR TOL ± 1.0 °													
4 PLACES		± 0.05											
3 PLACES		± 0.1											
2 PLACES		± 0.2											
1 PLACE		± 0.25		0.5 FPC CONN. HSG ASSY E/O STRAIGHT EMBSTP PKG (GOLD)									
0 PLACES		± 0.3											
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				PRODUCT CUSTOMER DRAWING									
				DOCUMENT NUMBER			DOC TYPE		DOC PART	REVISION			
				SD-501951-004			PSD		001	F			
THIRD ANGLE PROJECTION				DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
				A3-SIZE		501951				GENERAL MARKET		2 OF 2	